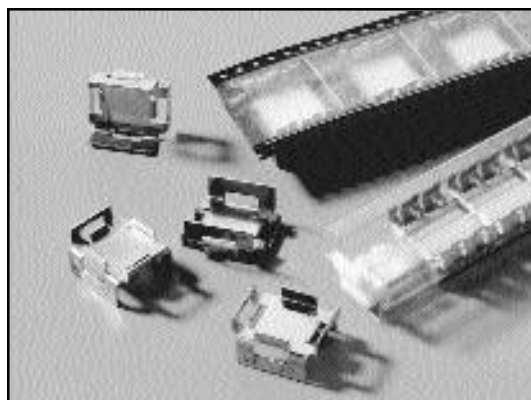


BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



217 SERIES Surface Mount Heat Sinks

D²PAK, TO-220, SOT-223, SOL-20

Compatible with surface mount technology (SMT) automated production techniques for ease of assembly and a variety of soldering methods, these heat sinks allow greater packaging densities and reduction in PC-board area, increasing the power dissipation of surface mount devices (SMDs) while maintaining and improving manufacturers' component thermal specifications.

FEATURES AND BENEFITS:

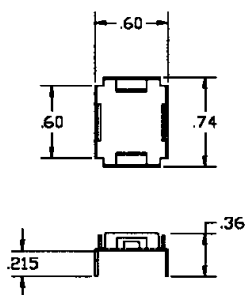
- No interface material is needed
- Copper with tin-lead plating for improved solderability and assembly
- Both the component and the heat sink are installed on the PC-board utilizing standard SMT assembly equipment for "Tape & Reel" and "Tube" formats
- EIA standards and ESD protection are specified
- Can be used with water soluble or no clean SMT solder creams or other pastes

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Package Format	Package Quantity	Thermal Performance at Typical Load Natural Convection	Forced Convection
217-36CT6 ▲	.390 (9.9)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTT6	.390 (9.9)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTR6▲	.390 (9.9)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM

Material: Copper, Tin, Lead Plated

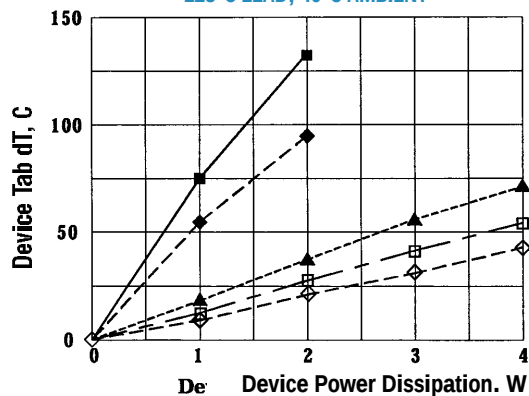
MECHANICAL DIMENSIONS

217 HEAT SINK WITH DPAK DEVICE

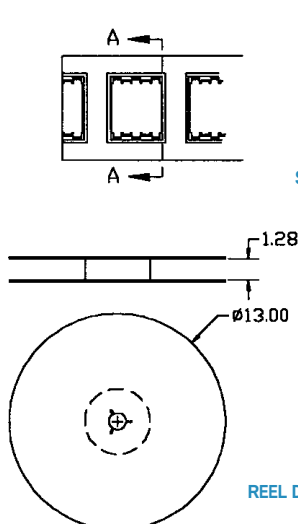


217-36CT6

THERMAL PERFORMANCE 6 LAYER BOARD, D² PAK 125°C LEAD, 40°C AMBIENT



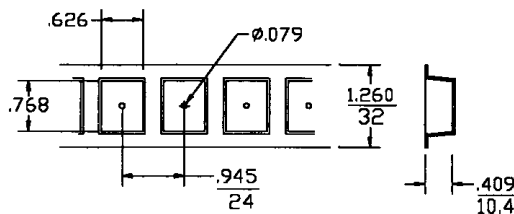
KEY: ■ Device only, NC ◆ Device + HS, NC ▲ Device + HS, 100 lfm □ Device + HS, 200 lfm ◇ Device + HS, 300 lfm



- NOTES
1. Material to be "ESD"
 2. Approximately 6 Meters per Reel
 3. 250 Pieces per Reel.

217-36CTR6

REEL DETAILS



TAPE DETAILS

Dimensions: in.

D²PAK, TO-220, SOL-20

REF: JEDEC TO-263 (DD PAK)
REF: JEDEC MO-169 (DD PAK)

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



PATENT PENDING

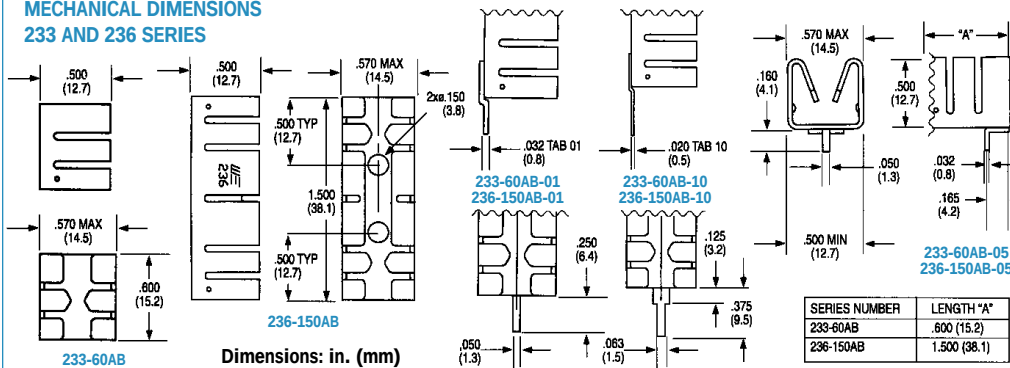
233 AND 236 SERIES Self-Locking Wavesolderable Heat Sinks

TO-220

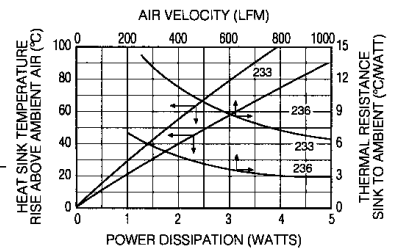
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
233-60AB ▲	.600 (15.2)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-01	.600 (15.2)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-05	.500 (12.7)	.600 (15.2) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-10 ▲	.725 (18.4)	.570 (14.5) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
236-150AB	1.500 (38.1)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
236-150AB-01	1.500 (38.1)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM
236-150AB-05 ▲	.500 (12.7)	1.500 (38.1) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM
236-150AB-10	1.625 (41.3)	.570 (14.5) x .570 (12.7)	Vertical	10	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS 233 AND 236 SERIES



NATURAL AND FORCED CONVECTION CHARACTERISTICS



SUGGESTED TAB HOLE =
Ø.075 (1.9) (PLATED)
WITH Ø.100 (2.5) PAD



PATENT 5381041

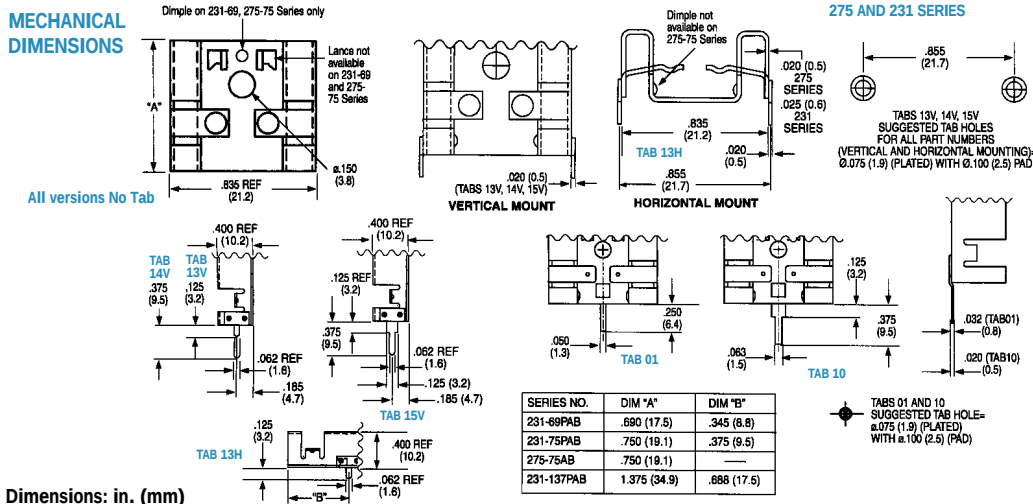
275 AND 231 SERIES Compact, Stress-Free Labor-Saving Locking-Tab Heat Sinks

TO-220

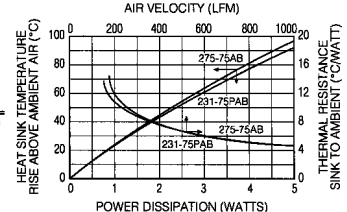
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
275-75AB	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
275-75AB-01	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vertical	01	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
275-75AB-10	.875 (12.7)	.835 (21.2) x .400 (14.5)	Vertical	10	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
231-69PAB	.690 (18.4)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PAB-13H	.400 (38.1)	.690 (17.5) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PAB-XXX	.690 (38.1)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-75PAB	.750 (12.7)	.835 (21.2) x .400 (14.5)	Vert./Horiz.	No Tab	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-75PAB-13H	.400 (41.3)	.750 (19.1) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
(14V) ▲ 231-75PAB-XXX	.750 (34.9)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-137PAB	1.375 (10.2)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
231-137PAB-13H	.400 (10.2)	1.375 (34.9) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
(15V) ▲ 231-137PAB-XXX	1.375 (10.2)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM

Material: Aluminum, Pre-anodized Black (PAB), Anodized Black (AB)

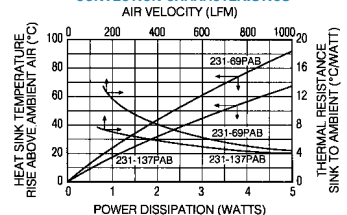
MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



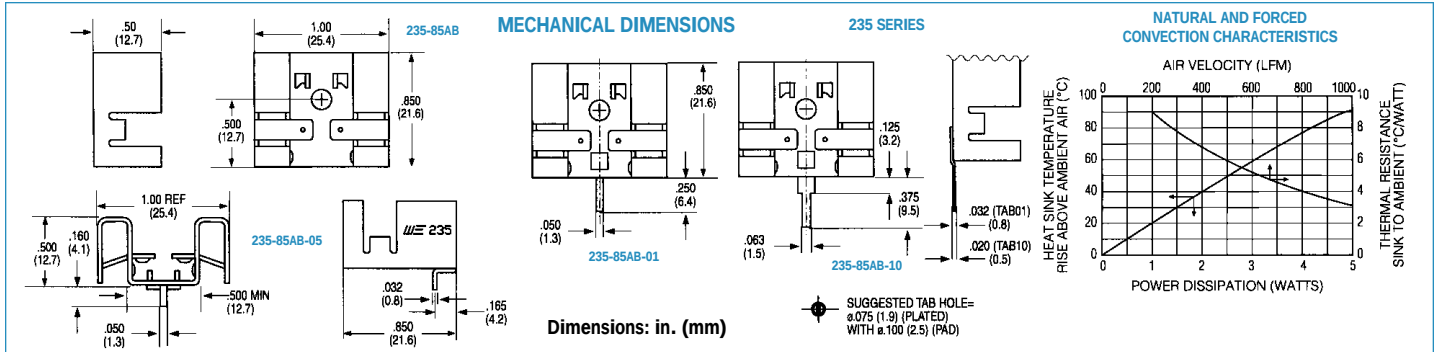
PATENT 5381041

235 SERIES Compact, Stress-Free Labor-Saving Locking-Tab Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
235-85AB ▲	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-01	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-05	.500 (12.7)	.850 (21.6) x 1.000 (25.4)	Horizontal	05	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-10	.975 (24.8)	1.000 (25.4) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM

Material: Aluminum, Black Anodized

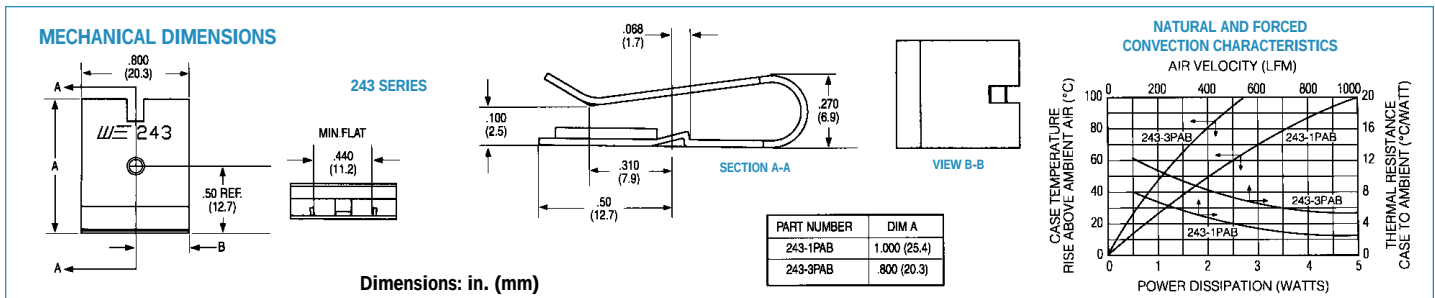


243 SERIES Labor-Saving Clip-On Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
243-1PAB	1.000 (25.4)	.800 (20.3) x .270 (6.9)	Vert./Horiz.	No Tab	Clip	50°C @ 2W	4.5°C/W @ 400 LFM
243-3PAB ▲	.800 (20.3)	.800 (20.3) x .270 (6.9)	Vert./Horiz.	No Tab	Clip	78°C @ 2W	8.2°C/W @ 400 LFM

Material: Aluminum, Pre-anodized Black



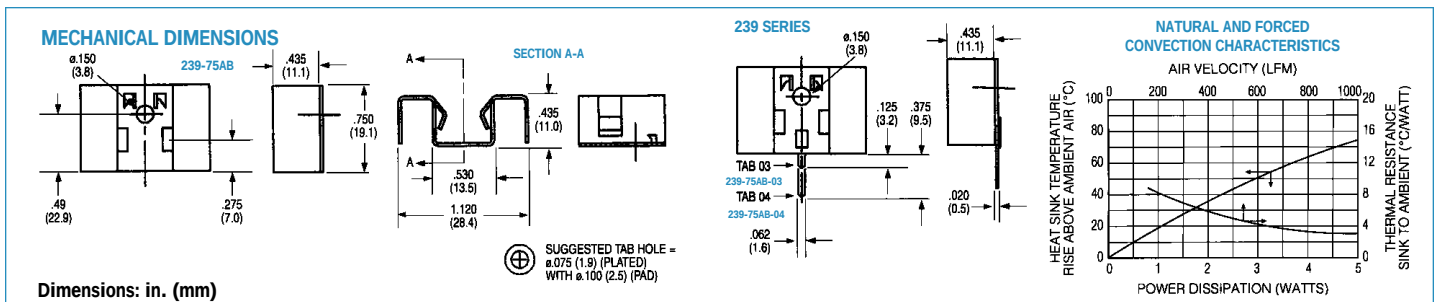
PATENT PENDING

239 SERIES Snap-Down Self-Locking Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
239-75AB	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vert./Horiz.	No Tab	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75AB-03	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	03	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75AB-04	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	04	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM

Material: Aluminum, Black Anodized



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



273 SERIES Low-Cost, Low-Height Wavesolderable Heat Sinks

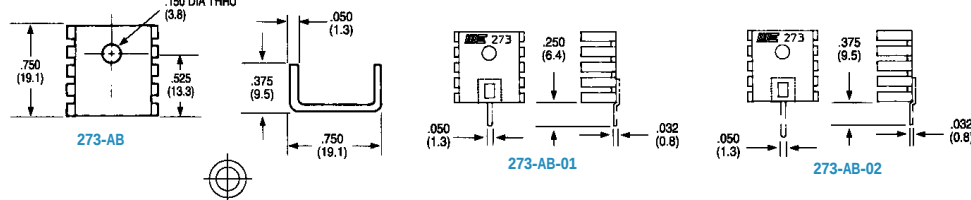
TO-218, TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
273-AB ▲	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-AB-01	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	01	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-AB-02	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	02	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

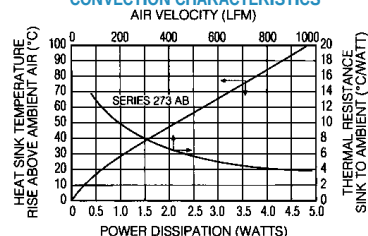
273 SERIES



Note:
1. Suggested Tab Hole = ϕ .075 (1.9) (Plated) with ϕ .100 (2.5) pad

Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



274 SERIES Low-Cost, Low-Height Wavesolderable Heat Sinks

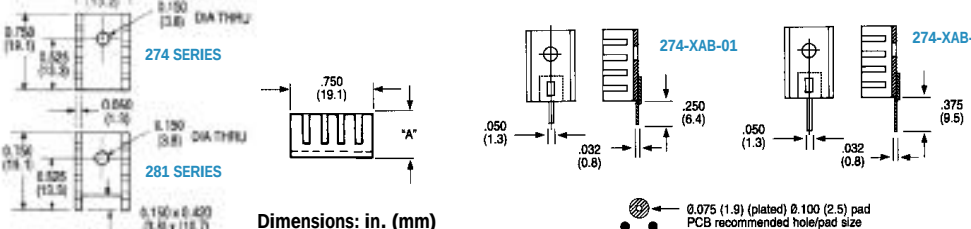
TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
274-1AB ▲	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1AB-01 ▲	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1AB-02	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-2AB ▲	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2AB-01	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2AB-02	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-3AB ▲	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3AB-01	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3AB-02	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
281-1AB	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
281-2AB	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

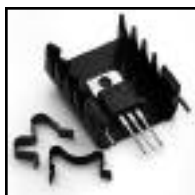
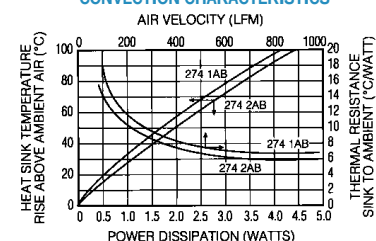
274 SERIES



Dimensions: in. (mm)

ϕ .075 (1.9) (plated) ϕ .100 (2.5) pad
PCB recommended hole/pad size

NATURAL AND FORCED CONVECTION CHARACTERISTICS



240 SERIES Labor-Saving Twisted Fin Heat Sinks

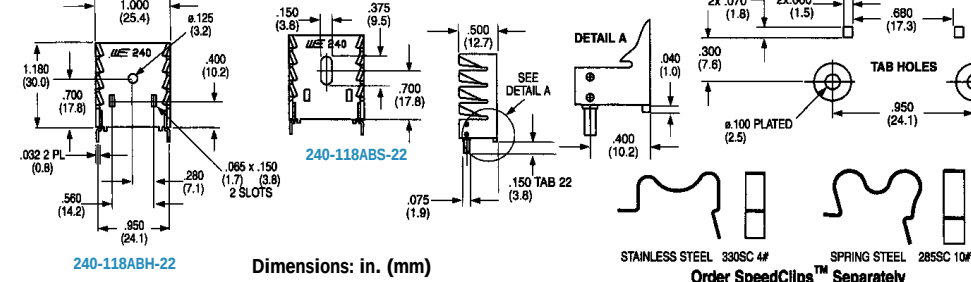
TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
240-118ABH-22 ▲	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Hole	55°C @ 4W	5.3°C/W @ 400 LFM
240-118ABS-22	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Slot	55°C @ 4W	5.3°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

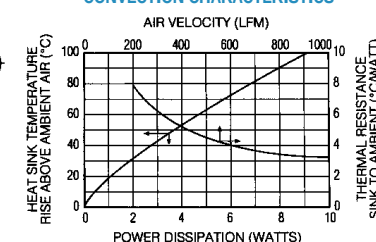
240 SERIES



Dimensions: in. (mm)

STAINLESS STEEL 330SC 4#
SPRING STEEL 285SC 10#
Order SpeedClips™ Separately

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

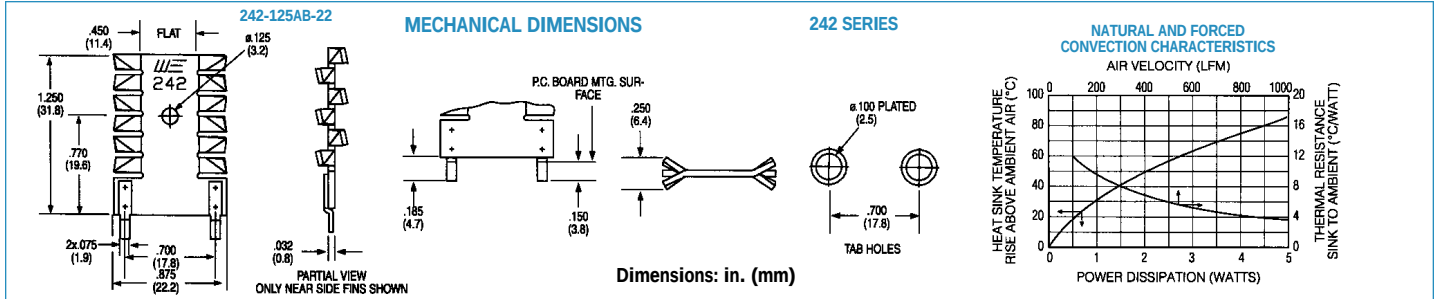


242 SERIES Low-Height, Low-Profile Twisted Fin Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
242-125AB-22	1.285 (32.6)	.875 (22.2) x .250 (6.4)	Vertical	22	Mtg Hole	48°C @ 2W	6.2°C/W @ 400 LFM

Material: Aluminum, Black Anodized

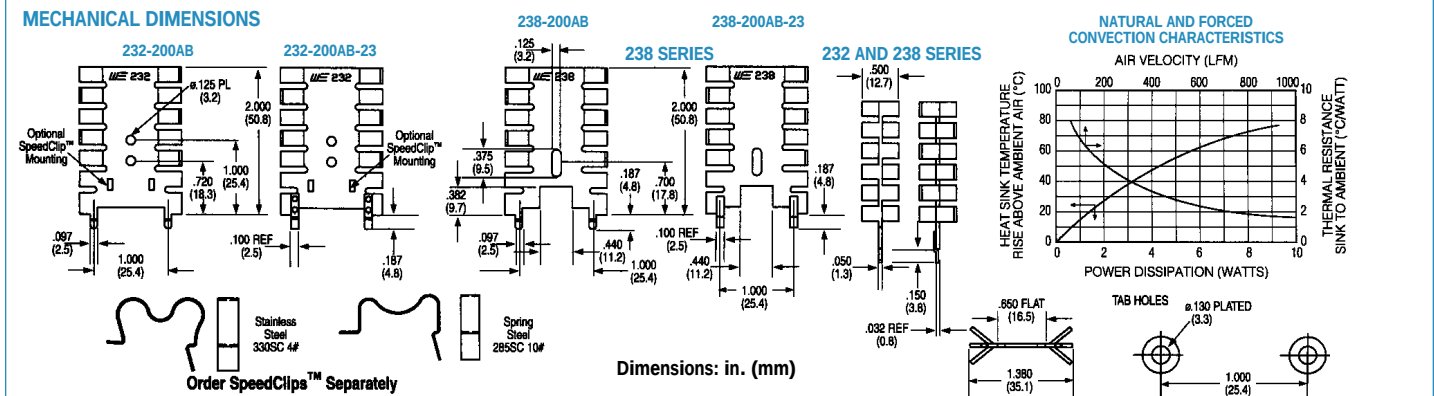


232 AND 238 SERIES Staggered Fin Heat Sinks for Vertical Mounting

TO-202, TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
232-200AB	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Twisted	Clip/Mtg Hole	48°C @ 4W	3.3°C/W @ 400 LFM
232-200AB-23	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Solderable	Clip/Mtg Hole	48°C @ 4W	3.3°C/W @ 400 LFM
238-200AB	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Twisted	Mtg Slot	48°C @ 4W	3.3°C/W @ 400 LFM
238-200AB-23	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Solderable	Mtg Slot	48°C @ 4W	3.3°C/W @ 400 LFM

Material: Aluminum, Black Anodized

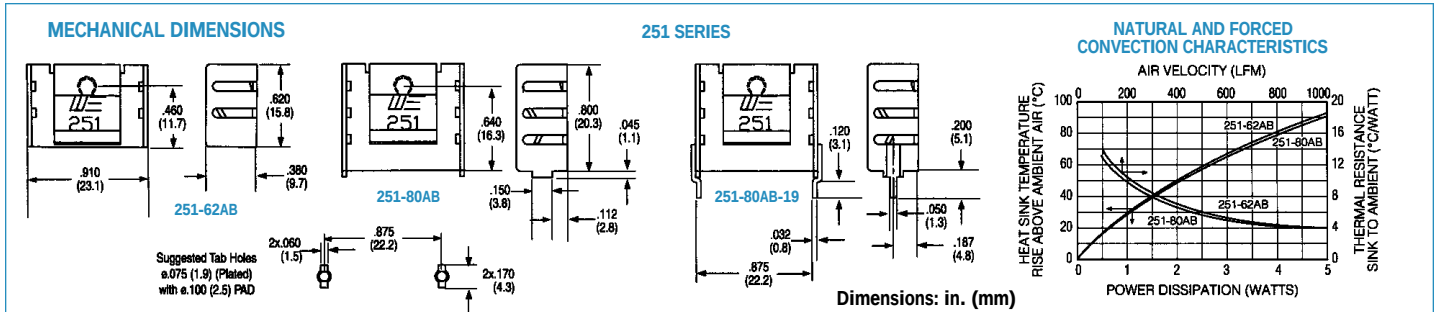


251 SERIES Slim-Profile Heat Sinks With Integral Clips

15 Lead Multiwatt

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
251-62AB	.620 (15.7)	.910 (23.1) x .380 (9.7)	Vert./Horiz.	No Tab	Clip	66°C @ 3W	66°C/W @ 400 LFM
251-80AB	.845 (21.5)	.910 (23.1) x .380 (9.7)	Vert./Horiz.	No Tab	Clip	64°C @ 3W	66°C/W @ 400 LFM
251-80AB-19	.875 (22.2)	.910 (23.1) x .380 (9.7)	Vertical	19	Clip	64°C @ 3W	66°C/W @ 400 LFM

Material: Aluminum, Black Anodized



BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 AND MULTIWATT™ COMPONENTS



244 SERIES

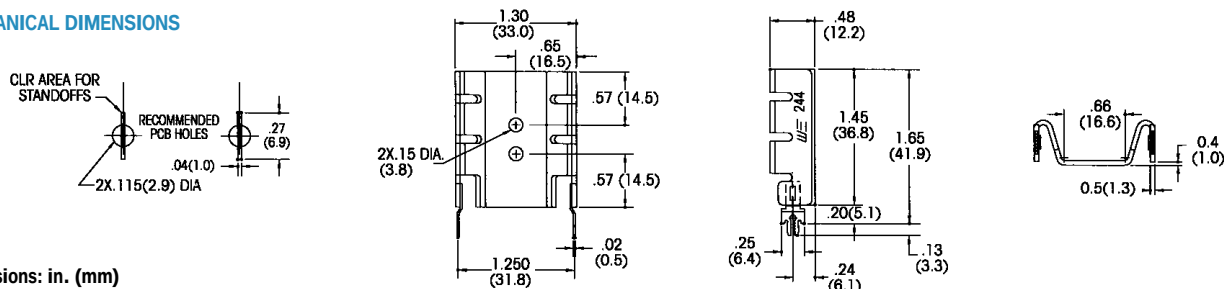
Low Height, Slim Profile Wavesolderable Folded Fin Heat Sinks

MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
244-145AB	1.450 (36.8)	1.300 (33.0) x .480 (12.1)	Vert./Horiz.	No Tab	44°C @ 4W	4.4°C/W @ 400 LFM	.0160 (7.25)
244-145AB-50	1.650 (41.9)	1.300 (33.0) x .480 (12.1)	Vertical	50	44°C @ 4W	4.4°C/W @ 400 LFM	.0170 (7.20)

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



245 SERIES

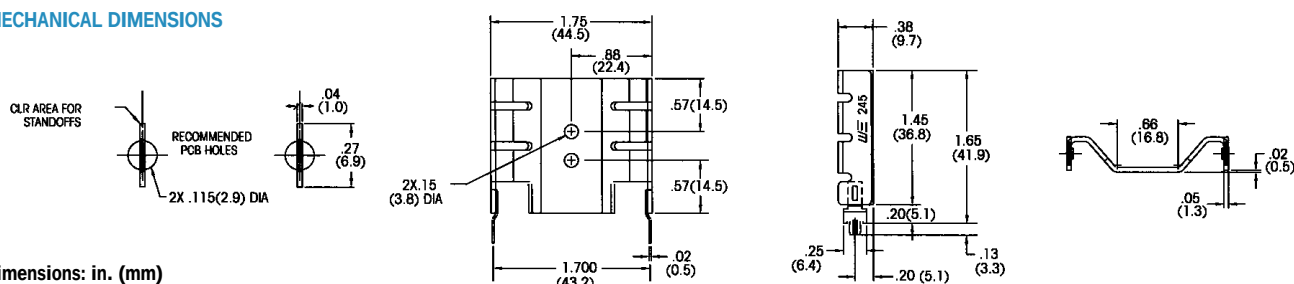
Low Height, Slim Profile Wavesolderable Folded Fin Heat Sinks

MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
245-145AB	1.450 (36.8)	1.750 (44.5) x .380 (9.7)	Vert./Horiz.	No Tab	38°C @ 4W	3.2°C/W @ 400 LFM	.0160 (7.25)
245-145AB-50	1.650 (41.9)	1.750 (44.5) x .380 (9.7)	Vertical	50	38°C @ 4W	3.2°C/W @ 400 LFM	.0170 (7.20)

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



246 SERIES

Medium Height, Slim Profile Wavesolderable Folded Fin Heat Sinks

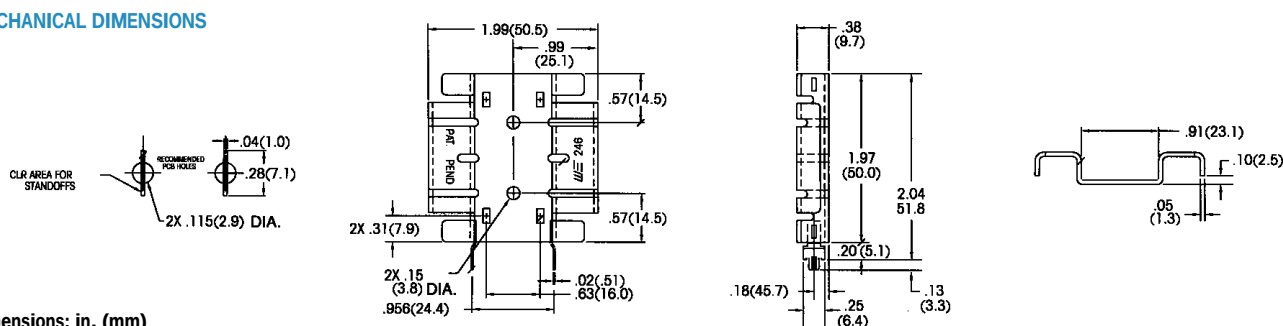
MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
246-197AB	1.968 (50.0)	1.986 (50.4) x 3.75 (9.5)	Vert./Horiz.	No Tab	35°C @ 4W	2.8°C/W @ 400 LFM	.0240 (10.90)
246-197AB-50	2.168 (55.1)	1.986 (50.4) x 3.75 (9.5)	Vertical	50	35°C @ 4W	2.8°C/W @ 400 LFM	.0250 (11.40)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 AND MULTIWATT™ COMPONENTS



247 SERIES Medium Height, Deep Profile Wavesolderable Folded Fin Heat Sinks

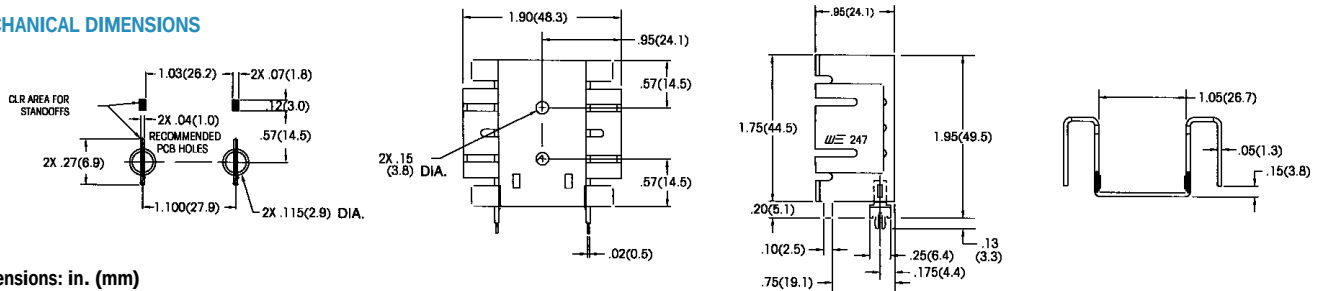
MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
247-195AB	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	25°C @ 4W	2.4°C/W @ 400 LFM	.0330 (15.10)
247-195AB-50	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vertical	50	25°C @ 4W	2.4°C/W @ 400 LFM	.0340 (15.60)

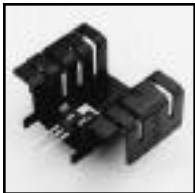
Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



248 SERIES Low Height, Medium Profile Wavesolderable Folded Fin Heat Sinks

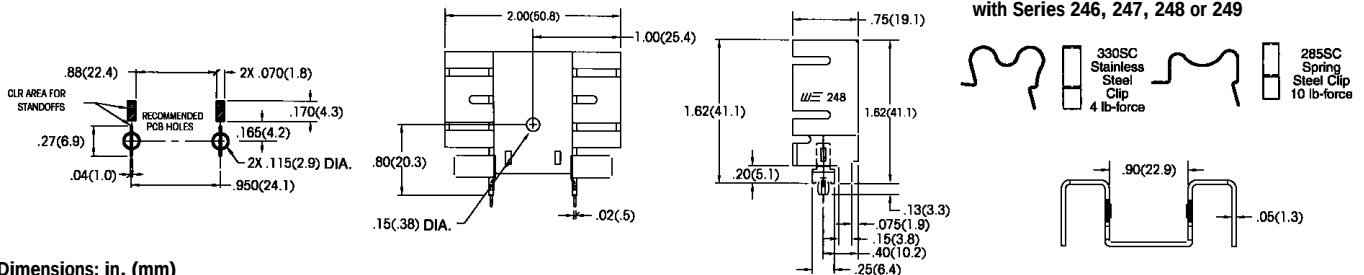
MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
248-162AB	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vert./Horiz.	No Tab	35°C @ 4w	2.5°C/W @ 400 LFM	.026 (11.60)
248-162AB-50	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vertical	50	35°C @ 4w	2.5°C/W @ 400 LFM	.027 (12.20)

Order SpeedClip™ 285SC or 330SC separately.

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



249 SERIES Medium Height, Deep Profile Wavesolderable Folded Fin Heat Sinks

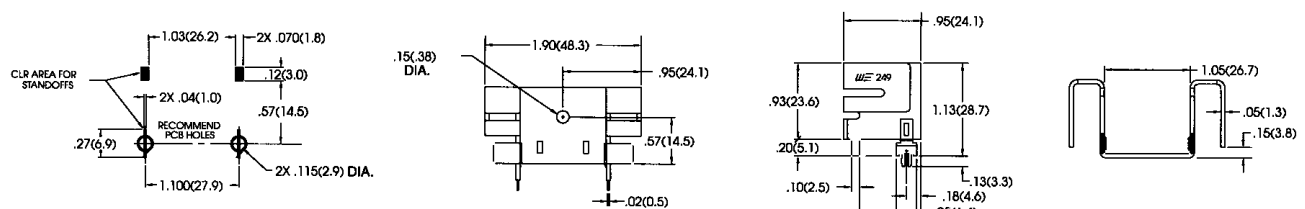
MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
249-113AB	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	35°C @ 4W	3.29°C/W @ 400 LFM	.020 (8.90)
249-113AB-50	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vertical	50	35°C @ 4W	3.29°C/W @ 400 LFM	.021 (9.40)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

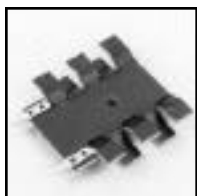
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



288 SERIES Compact Wave-Solderable Low-Cost Heat Sinks

TO-220, TO-202

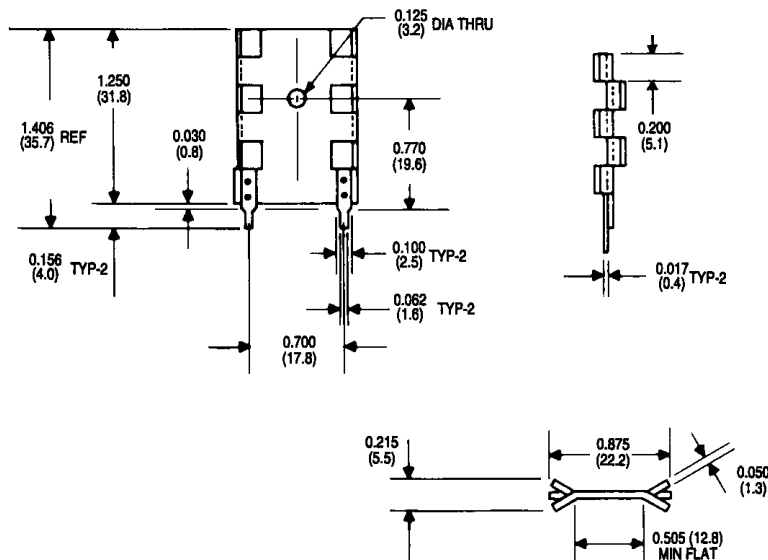
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
288-1AB ▲	1.250 (31.8)	0.875 (22.2) x 0.215 (5.5)	85°C @ 4W	12°C/W @ 200 LFM	0.0057 (2.59)

Mounting tabs are pre-tinned to ensure excellent wave-solder bond and good electrical connections for vertical mounting of TO-220 and TO-202 semiconductor packages. These heat sinks are designed for use where minimum PC

board space is available. The 288-1AB is a stamped aluminum heat sink, black anodized, designed for applications requiring good heat dissipation from a heat sink occupying minimum space, available at minimum cost.

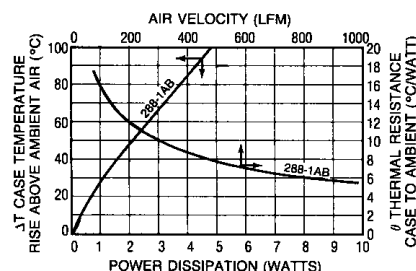
MECHANICAL DIMENSIONS

288 SERIES



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



271 SERIES Top-Mount Booster Heat Sinks for Use with 270/272/280 Series

TO-220

Standard P/N	Height Above Semiconductor Case in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
271-AB ▲	0.500 (12.7)	1.750 (44.5) x 0.700 (17.8)	62°C @ 4W (NOTE A) 31 °C @ 4W (NOTE B)	5.1°C/W @ 400 LFM 1.8°C/W 400 LFM (NOTE B)	0.0052 (2.36)

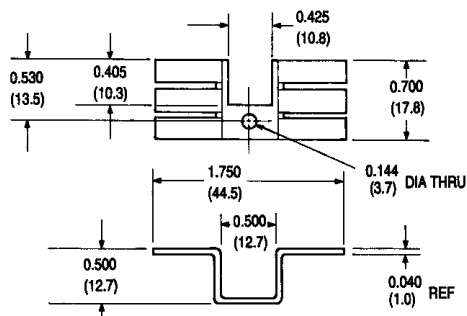
Material: Aluminum, Black Anodized

This top-hat style booster heat sink can be added to any of the 270, 272, or 280 Series for improved performance.

NOTE A: Thermal resistance with one 271-AB. NOTE B: Thermal resistance (total) as shown with (2) 271-AB types added to (1) 272-AB type.

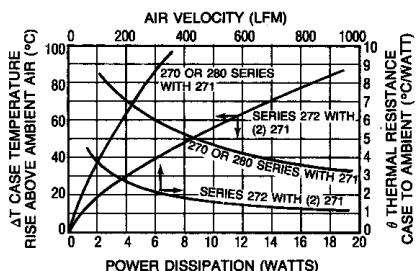
MECHANICAL DIMENSIONS

271 SERIES



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS


270/272/280 SERIES Small Footprint Low-Cost Heat Sinks

TO-220, TO-202

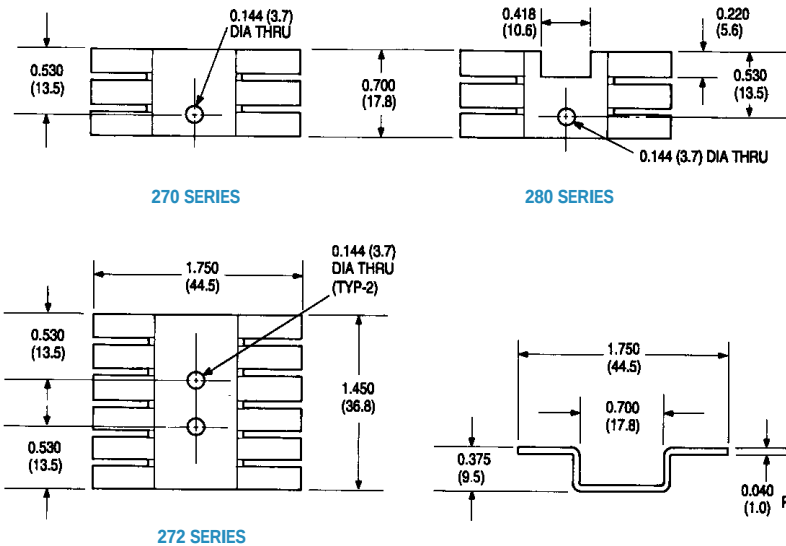
Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
270-AB ▲	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0052 (2.36)
272-AB ▲	0.375 (9.4)	1.750 (44.5) x 1.450 (36.8)	01,02	42°C @ 4W	3.6°C/W @ 400 LFM	0.0105 (5.72)
280-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0048 (2.18)

Material: Aluminum, Black Anodized

These exceptionally low-cost heat sinks can be mounted horizontally under a TO-220 or TO-202 case style with a maximum height of only 0.375 in. (9.4). For added performance, a 271 Series heat sink can also be used for double-sided heat dissipation.

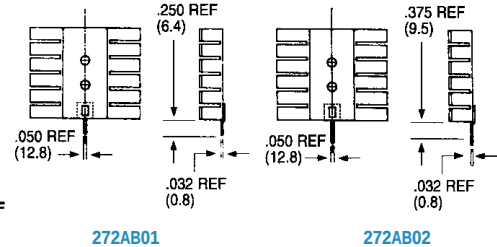
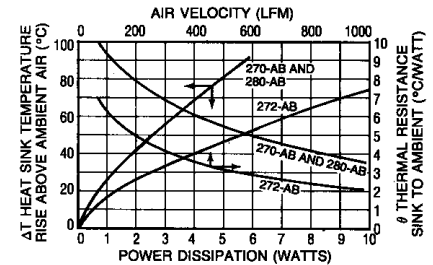
The 270-AB and 280-AB accept one power semiconductor; the 272-AB is designed for two power semiconductors. Specify solderable tab options for the 272 Series by the addition of suffix "01" or "02" to the standard part number (i.e. 272-AB01 or 272-AB02).

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Note:
1. Suggested Tab Hole = 0.075 ±.003 plated with 0.100 pad


289 AND 290 SERIES Low-Cost Single or Dual Package Heat Sinks

TO-218, TO-202, TO-220

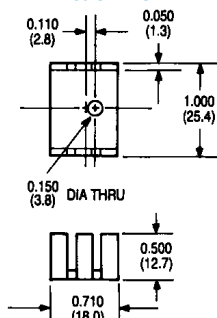
Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
289-AB ▲	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	44°C/W @ 400 LFM	0.0055 (2.49)
289-AP	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	44°C/W @ 400 LFM	0.0055 (2.49)
290-1AB ▲	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	35°C/W @ 400 LFM	0.0082 (3.72)
290-2AB ▲	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	35°C/W @ 400 LFM	0.0081 (3.67)

Material: Aluminum, Black Anodized

Low in cost and compact in overall dimensions, one 289 Series heat sink can accommodate one semiconductor; the 289 Series is available with a black anodized finish (289-AB) or with

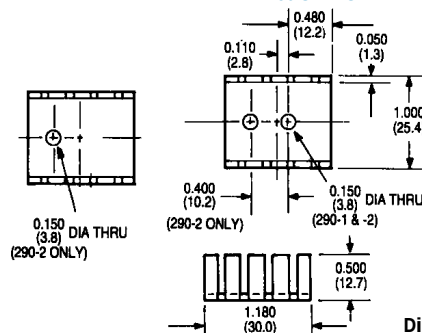
no finish (289-AP). Two semiconductors can be mounted to the 290-2AB style.

289 SERIES



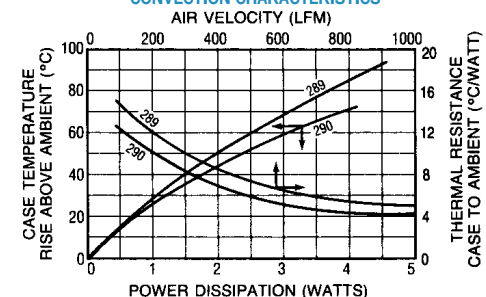
MECHANICAL DIMENSIONS

290 SERIES



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS

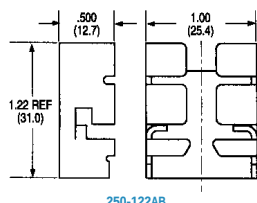


Multiwatt

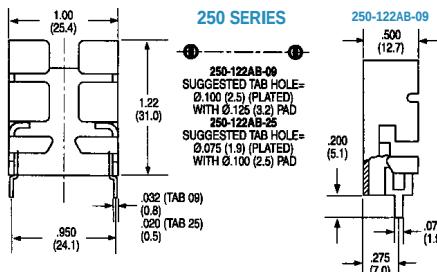
Standard P/N	Height Above	Footprint	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
	PC Board in. (mm)	Dimensions in. (mm)				Natural Convection	Forced Convection
250-122AB	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122AB-09 ▲	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vertical	09	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122AB-25	1.380 (35.1)	1.000 (25.4) x .500 (12.7)	Vertical	25	Clip	50°C @ 4W	3.7°C/W @ 400 LFM

Material: Aluminum. Black Anodized

250 SERIES



Dimensions: in. (mm)



The graph illustrates the relationship between power dissipation, air velocity, and temperature rise. The x-axis represents Power Dissipation (Watts) from 0 to 10. The top x-axis represents Air Velocity (LFM) from 0 to 1000. The left y-axis represents Heat Sink Temperature Rise Above Ambient Air (°C) from 0 to 100. The right y-axis represents Thermal Resistance Sink to Ambient (°C/Watt) from 0 to 10. Two curves are shown: one for temperature rise (increasing with power) and one for thermal resistance (decreasing with power).

Power Dissipation (Watts)	Air Velocity (LFM)	Heat Sink Temperature Rise Above Ambient Air (°C)	Thermal Resistance Sink to Ambient (°C/Watt)
0	0	0	10
2	200	20	5
4	400	40	2.5
6	600	60	1.7
8	800	80	1.25
10	1000	100	1

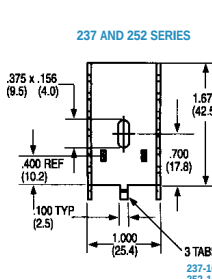


TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
237-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg Slot	46° C @ 4W	4.5° C/W @ 200 LFM
237-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg Slot	46° C @ 4W	4.5° C/W @ 200 LFM
237-167AB2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg Slot	46° C @ 4W	4.5° C/W @ 200 LFM
252-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg Slot	40° C @ 4W	4.5° C/W @ 200 LFM
252-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg Slot	40° C @ 4W	4.5° C/W @ 200 LFM
252-167AB2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg Slot	40° C @ 4W	4.5° C/W @ 200 LFM

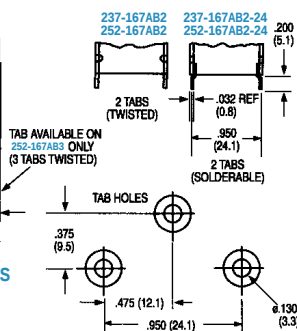
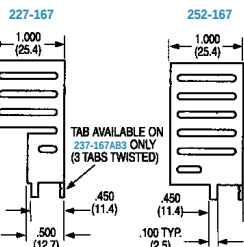
Order SpeedClips™ 285SC or 330SC separately for rapid component installation, lowering manufacturing costs. Material: Aluminum. Black Anodized.

227-167

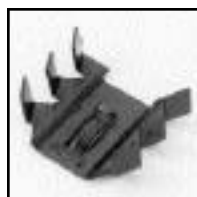
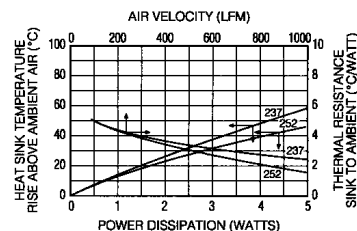
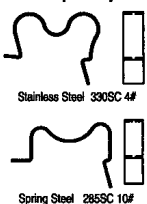


237 AND 252 SERIES

Dimensions: in. (mm)



Order SpeedClips™ Separately



TO-220

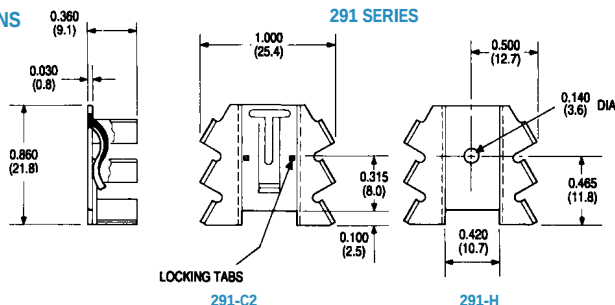
Standard P/N	Height Above PC Board in. (mm)	Vertical Mounting Footprint Dimensions in. (mm)	Mounting Style	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
291-C236AB	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Clip)	80° C @ 2W	24° C/W @ 600 LFM	0.0026 (1.18)
291-H36AB ▲	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Mtg. Hole)	68° C @ 2W	16° C/W @ 600 LFM	0.0026 (1.18)▲

Material: Aluminum, Black Anodized

Designed for mounting horizontally or vertically on a circuit board, 291 Series heat sinks employ a unique clip for attachment of TO-220 case styles.

One type is available with a locking clip and one with a 0.140 in. (3.6) diameter mounting hole only.

291 SERIES

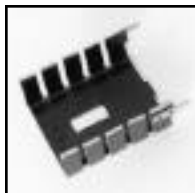
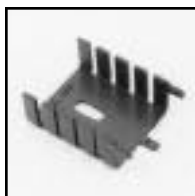


Dimensions: in. (mm)

The graph plots Case Temperature Rise Above Ambient (°C) on the Y-axis (0 to 100) against Power Dissipation (Watts) on the X-axis (0 to 5). It also features a top X-axis for Air Velocity (LFM) (300 to 1500) and a right Y-axis for Thermal Resistance (°C/W) (10 to 40). Two diode models are shown: 291-C236AB and 291-H36AB. Arrows indicate the corresponding curves for each model.

Power Dissipation (Watts)	Case Temp Rise (°C) - 291-C236AB	Case Temp Rise (°C) - 291-H36AB	Thermal Resistance (°C/W) - 291-C236AB	Thermal Resistance (°C/W) - 291-H36AB
0	0	0	40	10
1	20	10	30	10
2	40	15	25	10
3	60	18	20	10
4	80	19	18	10
5	100	20	17	10

TO-220



TO-220



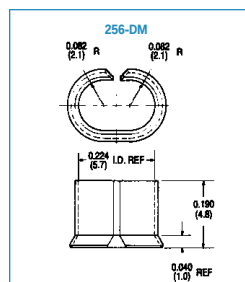
STUD-MOUNT

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



256 SERIES Thermal Retainers

Standard P/N	Height (Less Mounting Tab) in. (mm)	Material	Weight lbs. (grams)
256-DM ▲	0.190 (4.0)	Beryllium Copper	0.0005 (0.23)



TO-92

260 SERIES Cup Clips for TO-5 Case Style Semiconductors

TO-5

Characteristics

	TO-5
Thermal Resistance – Epoxy Insulated	14° C/W
Thermal Resistance – Beryllium Oxide Insulated	16° C/W
Breakdown Voltage – Epoxy Type (VAC), 60 Hz	500
Breakdown Voltage – Beryllium Type (VAC), 60 Hz	1000
Recommended Operating Voltage, AC or DC	
Clean Conditions: % Hipot Rating	50
Dusty Conditions: % Hipot Rating	30
Dirty Conditions: % Hipot Rating	10 to 20
Temperature Range — Continuous (C°)	-73/+149

Model	Depth of Tapped Base
260-4T5E	0.093 (2.36)
260-4TH5E	0.125 (3.18)
260-4TH5B	0.125 (3.18)

Thread

Size:	4 = #4-40 UNC
	6 = #6-32 UNC
	10 = #10-32 UNF

Mounting Style:	T = tapped
	S = stud
	P = plain

Base Style:	H = hex
Semiconductor Case Style:	5 = TO-5
Insulation Type:	E = epoxy
	B = beryllium



TO-5 CASE STYLE CUP CLIPS — ORDERING GUIDE

Standard P/N	Insulation Type	Outline Dimension L x W x I.D. in. (mm)	Weight lbs. (grams)	Case Style
260-4T5E ▲	Epoxy Insulated	0.370 (9.4) x 0.380 (9.7) dia. x 0.290 (7.4)	0.0024 (1.09)	TO-5
260-4TH5E ▲	Epoxy Insulated	0.400 (10.2) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0031 (1.41)	TO-5
260-6SH5E ▲	Epoxy Insulated	0.557 (14.1) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0037 (1.68)	TO-5
260-10SH5E	Epoxy Insulated	0.557 (14.1) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0042 (1.91)	TO-5
260-4TH5B ▲	Beryllium Oxide Insulated	0.445 (11.3) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0042 (1.91)	TO-5
260-6SH5B ▲	Beryllium Oxide Insulated	0.607 (15.4) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0039 (1.77)	TO-5
260-10SH5B	Beryllium Oxide Insulated	0.607 (15.4) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0043 (1.95)	TO-5

Materials and Finish: Cups – beryllium copper, black ebonol "C"; Bases – brass, black ebonol "C"; Ceramic Spacers – beryllium oxide

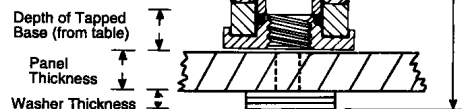
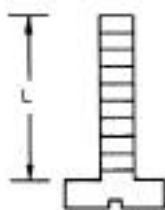
Base Mounting Configurations — TO-5

Plain Type — Epoxy bonded, or used with #4 pan head screws.

Tapped Base — #4-40 UNC screw (not supplied) fits tapped hole. Care should be taken not to use too long a screw, which could short against the semiconductor case. For correct screw lengths:

Correct Screw Length (L) = Depth of Base + Panel Thickness + Washer Thickness

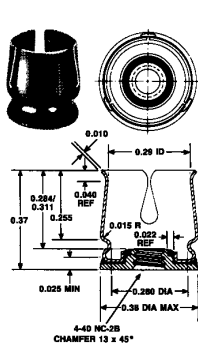
Stud Mounting Base. #6-32 UNC or #10-32 UNF studs. Nuts and washers not supplied. Stud hole must be slightly countersunk to ensure flat mounting.



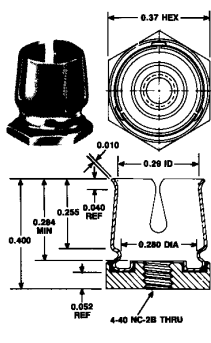
To determine the correct mounting screw lengths, add dimensions as follows:

Correct Screw Length (L) = Depth of Base + Panel Thickness + Washer Thickness

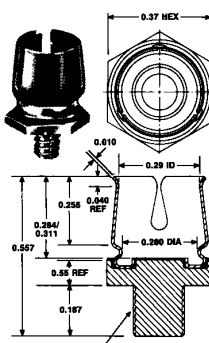
Epoxy Insulated For TO-5



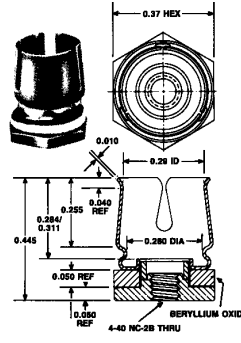
▲ 260-4T5E



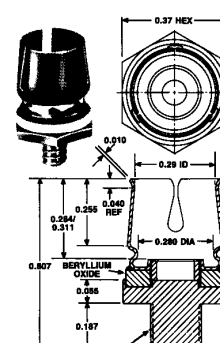
▲ 260-4TH5E

260-6SH5E
260-10SH5E

Beryllium Oxide Insulated For TO-5



▲ 260-4TH5B

▲ 260-6SH5B
260-10SH5B

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



634 SERIES Slim Profile Unidirectional Fin Vertical Mount Heat Sink

TO-220 and TO-218

Plain Pin	Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Weight lbs. (grams)
	Without Pin			
634-10ABP ▲	634-10AB	1.000 (25.4)	0.640 (16.26) x 0.640 (16.26)	0.016 (7.48)
634-15ABP	634-15AB	1.500 (38.1)	0.640 (16.26) x 0.640 (16.26)	0.025 (11.21)
634-20ABP ▲	634-20AB	2.000 (50.8)	0.640 (16.26) x 0.640 (16.26)	0.033 (14.95)

Material: Aluminum, Black Anodized.

These slim profile unidirectional fin heat sinks offer users two assembly alternatives for vertically mounting TO-220 and TO-218 components. Models are available with or without wave-

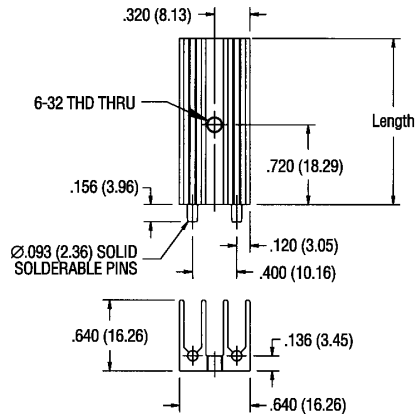
solderable pins on 0.40 in. (10.2) centers, making them ideal for a variety of applications where quick assembly is needed and space is at a premium.

MECHANICAL DIMENSIONS

634 SERIES

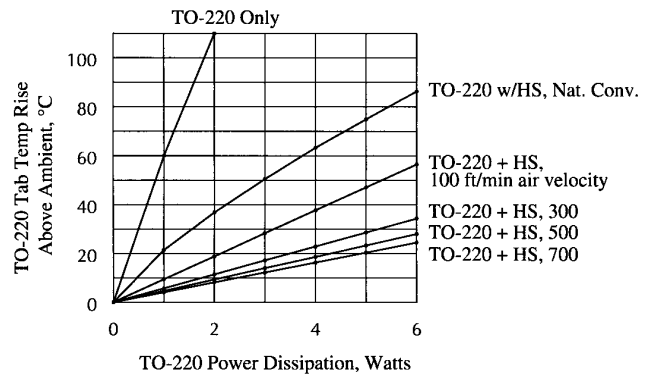
Notes:

1. Thermal compound is assumed between device and heat sink.
2. Tab temp with longer heat sink (634-20ABP) will typically be about 15% cooler. Tab temp with shorter heat sink (634-10ABP) will typically be about 25% higher.



Dimensions: in. (mm)

TYPICAL THERMAL PERFORMANCE FOR 634-15ABP



637 SERIES High-Efficiency Heat Sinks For Vertical Board Mounting

TO-220

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
637-10ABP ▲	1.000 (25.4)	1.375 (34.9) x 0.500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM	0.023 (10.43)
637-15ABP ▲	1.500 (38.1)	1.375 (34.9) x 0.500 (12.7)	65°C @ 6w	5.5°C/W @ 200 LFM	0.035 (15.88)
637-20ABP ▲	2.000 (50.8)	1.375 (34.9) x 0.500 (12.7)	55°C @ 6W	4.7°C/W @ 200 LFM	0.050 (22.68)
637-25ABP ▲	2.500 (63.5)	1.375 (34.9) x 0.500 (12.7)	48°C @ 6W	4.2°C/W @ 200 LFM	0.062 (28.12)

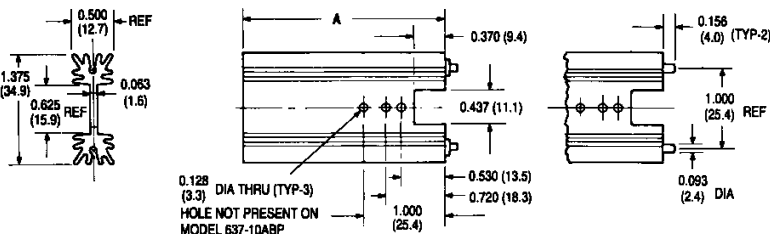
Material: Aluminum, Black Anodized

Wave-solderable pins on 1 in. centers for vertical mounting on printed circuit boards. Maximum semiconductor package width 0.625 in. (15.9). Use this heat sink where weight

and board space occupied must be minimized. Refer to the Accessory products section for thermal interface materials, thermal compounds, and other accessories products.

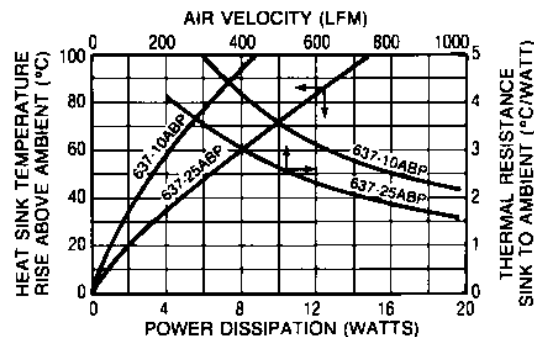
MECHANICAL DIMENSIONS

637 SERIES (EXTRUSION PROFILE 5183)

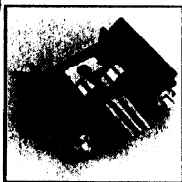


Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



667 SERIES Labor-Saving SpeedClip™ Heat Sinks for Vertical Board Mounting

TO-220

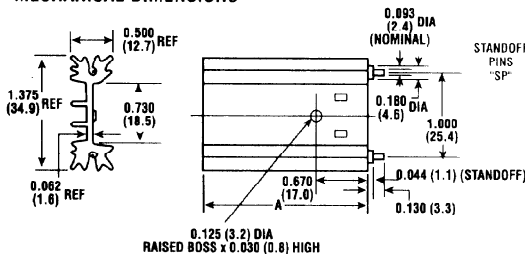
Standard P/N	Plain Pin	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs (grams)
667-10ABSP ▲	667-10ABPP ▲	1.000 (25.4)	1.375 (34.9) x 0.500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM	0.0240 (11.0)
667-15ABSP ▲	667-15ABPP ▲	1.500 (38.1)	1.375 (34.9) x 0.500 (12.7)	66°C @ 6W	5.5°C/W @ 200 LFM	0.0340 (15.6)
667-20ABSP ▲	667-20ABPP ▲	2.000 (50.8)	1.375 (34.9) x 0.500 (12.7)	58°C @ 6W	4.7°C/W @ 200 LFM	0.0460 (21.0)
667-25ABSP ▲	667-25ABPP ▲	2.500 (63.5)	1.375 (34.9) x 0.500 (12.7)	48°C @ 6W	4.2°C/W @ 200 LFM	0.0580 (26.2)

Wave-solderable pins. Material: Aluminum, Black Anodized

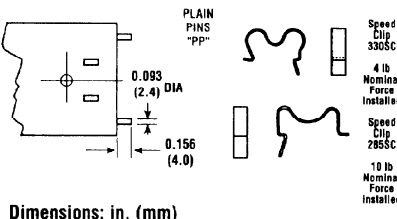
Excellent performance, choice of wave-solderable plain pins (PP-Type) or wave-solderable hex-shaped standoff pins (SP-Type), and reduced assembly cost.

Note: Order 330 SC or 285 SC SpeedClip™ separately.

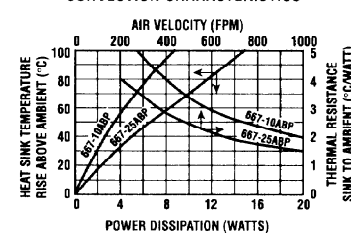
MECHANICAL DIMENSIONS



667 SERIES (EXTRUSION PROFILE 8073)



NATURAL AND FORCED CONVECTION CHARACTERISTICS



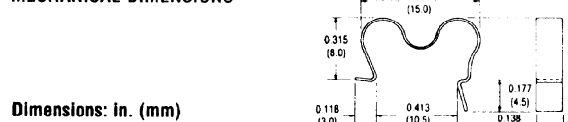
285 AND 330 SERIES 285 SC and 330 SC SpeedClips™ for 667 Series Heat Sinks

Standard P/N	Nominal Installed Loading Force	For Use With Series	Material	Weight lbs. (grams)
285 SC	10 lbs	232, 237, 240, 252, 667	Carbon Steel	0.00053 (0.24)
330 SC	4 lbs	232, 237, 240, 252, 667	Stainless Steel	0.00074 (0.34)

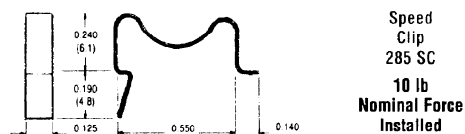
SpeedClips™ employ a locking safety tab for mounting. Must be ordered separately for these heat sink series. Use these SpeedClips™ with our 237, 240, 252, and 667 Series heat sinks

for the lowest production assembly time and cost. Order one SpeedClip™ for each 667 Series heat sink purchased.

MECHANICAL DIMENSIONS



Speed Clip
330 SC
4 lb
Nominal Force
Installed



Speed Clip
285 SC
10 lb
Nominal Force
Installed



647 SERIES High-Performance Heat Sinks for Vertical Board Mounting

TO-220

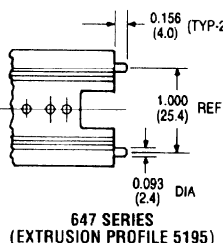
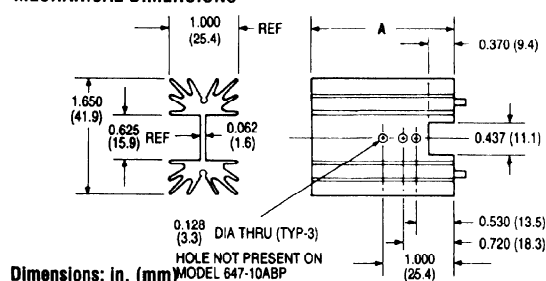
Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
647-10ABP ▲	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	42°C @ 6W	3.8°C/W @ 200 LFM	0.055 (24.95)
647-15ABP ▲	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	37°C @ 6W	3.5°C/W @ 200 LFM	0.075 (34.02)
647-175ABP ▲	1.750 (44.5)	1.650 (41.9) x 1.000 (25.4)	34°C @ 6W	3.3°C/W @ 200 LFM	0.090 (40.82)
647-20ABP ▲	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	31°C @ 6W	3.1°C/W @ 200 LFM	0.104 (47.17)
647-25ABP ▲	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.8°C/W @ 200 LFM	0.125 (56.70)

Material: Aluminum, Black Anodized

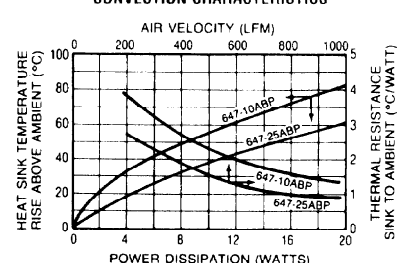
Wave-solderable pins on 1 in. centers for vertical mounting of larger devices on printed circuit boards. Maximum semiconductor package width: 0.625 (15.9). Refer to the Accessory

Products section for thermal interface materials, 126 Series silicone-free thermal compounds, and other accessories products.

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



626 AND 627 SERIES High-Efficiency Heat Sinks for Vertical Board Mounting

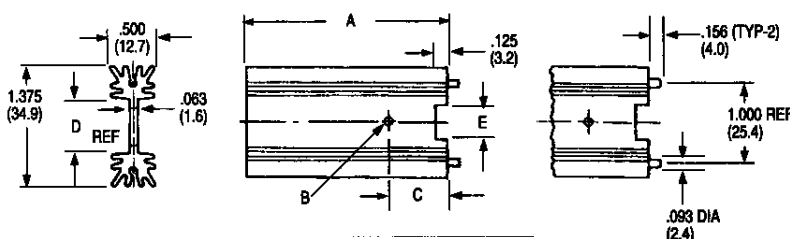
TO-218, TO-220

Standard P/N	Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
				Natural Convection	Forced Convection
626-10ABP	627-10ABP	1.000 (25.4)	1.375 (34.9) x .500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM
626-15ABP	627-15ABP	1.500 (38.1)	1.375 (34.9) x .500 (12.7)	65°C @ 6W	5.5°C/W @ 200 LFM
626-20ABP	627-20ABP	2.000 (50.8)	1.375 (34.9) x .500 (12.7)	55°C @ 6W	4.7°C/W @ 200 LFM
626-25ABP	627-25ABP	2.500 (63.5)	1.375 (34.9) x .500 (12.7)	48°C @ 6W	4.2°C/M @ 200 LFM

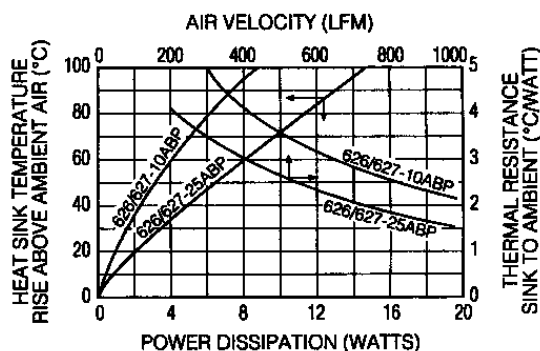
Wave-solderable pins. Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

626 AND 627 SERIES



NATURAL AND FORCED CONVECTION CHARACTERISTICS



Series	Type Device	Hole Diameter "B" in. (mm)	Hole Height "C" in. (mm)	Webb Width "D" in. (mm)	Notch Width "E" in. (mm)	Extrusion Profile
626	TO-218	.144 (3.7)	.850 (21.6)	.660 (16.8)	.540 (13.7)	8420
627	TO-220	.128 (3.3)	.720 (18.3)	.625 (15.9)	.437 (11.1)	5183

Dimensions: in. (mm)



657 SERIES High-Performance Heat Sinks for Vertical Board Mounting

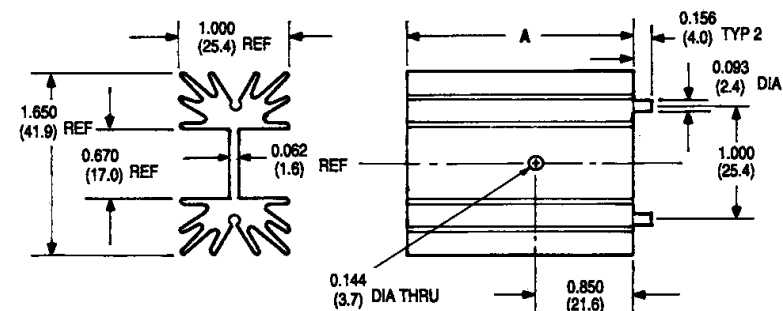
TO-220, TO-247, TO-218

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs (grams)
			Natural Convection	Forced Convection	
657-10ABP ▲	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM	0.0515 (23.36)
657-15ABP ▲	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM	0.0760 (34.60)
657-20ABP ▲	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM	0.1030 (47.00)
657-25ABP ▲	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM	0.1250 (57.00)

Wave-solderable pins. Material: Aluminum, Black Anodized

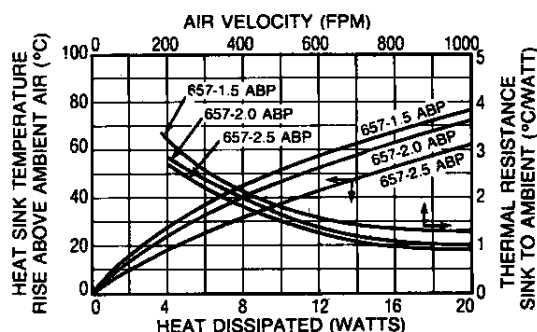
MECHANICAL DIMENSIONS

657 SERIES

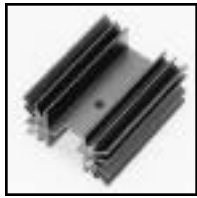


Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



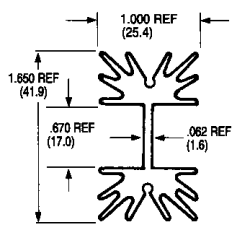
657 SERIES High-Performance Notched Heat Sinks for Vertical Board Mounting

TO-220, TO-247, TO-218

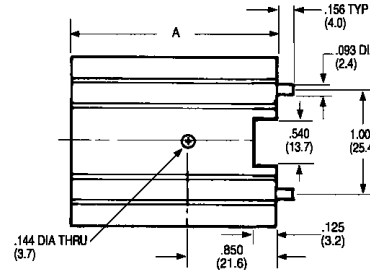
Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
657-10ABPN	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM
657-15ABPN ▲	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM
657-20ABPN	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM
657-25ABPN	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM

Wave-solderable pins. Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



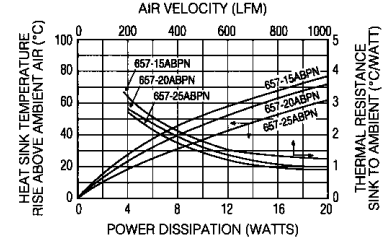
Dimensions: in. (mm)



657 SERIES

657 SERIES
(EXTRUSION PROFILE 6533)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



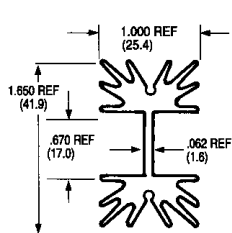
657 SERIES High-Performance Heat Sinks with SpeedClips™ for Vertical Board Mounting

TO-220, TO-247, TO-218

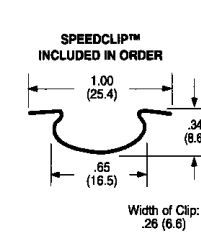
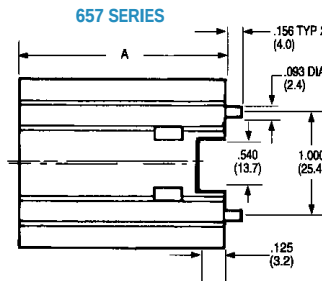
Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
657-10ABPSC	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM
657-15ABPSC	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM
657-20ABPSC	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM
657-25ABPSC ▲	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM

Wave-solderable pins. Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

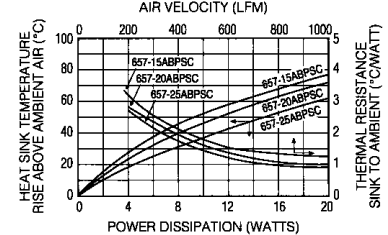


Dimensions: in. (mm)



657 SERIES
(EXTRUSION PROFILE 6533)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



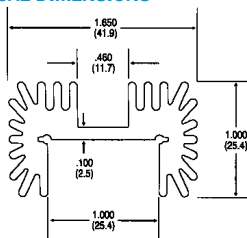
677 SERIES High-Performance, High-Power Heat Sinks for Vertical Board Mounting

TO-218, TO-220, TO-247
15-LEAD Multiwatt

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
677-10ABP	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	52°C @ 6W	3.1°C/W @ 200 LFM
677-15ABP	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	46°C @ 6W	2.8°C/W @ 200 LFM
677-20ABP	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	40°C @ 6W	2.5°C/W @ 200 LFM
677-25ABP	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	35°C @ 6W	2.2°C/W @ 200 LFM

Wave-solderable pins. Material: Aluminum, Black Anodized

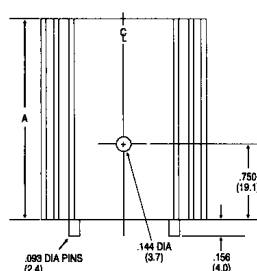
MECHANICAL DIMENSIONS



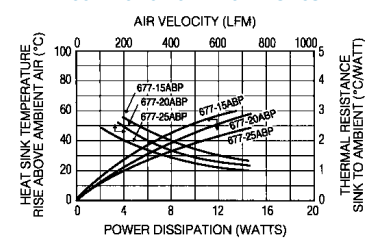
Dimensions: in. (mm)

677 SERIES

677 SERIES
(EXTRUSION PROFILE 8719)



NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



690 SERIES Highest Efficiency/Lowest Unit Cost Heat Sinks

TO-3, TO-66, TO-220

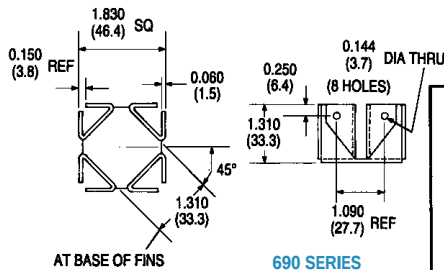
Standard P/N	Height Above PC Board in. (mm)	Outline Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
690-3B ▲	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-3	0.0700 (31.75)
690-66B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-66	0.0700 (31.75)
690-220B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(2) TO-220	0.0700 (31.75)

Material: Aluminum, Black Anodized

These low-cost heat sinks provide the most power dissipation at the lowest unit cost and are available in three standard types to mount and cool one TO-3 or TO-66 metal power semiconductor type or two plastic package TO-220 power semiconductor types. For higher power

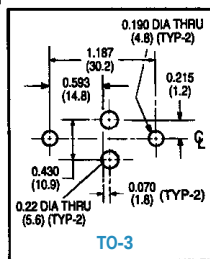
semiconductors, the 690 Series can dissipate up to 20 watts while maintaining a mounting surface temperature rise above ambient air temperature of no more than 91°C.

MECHANICAL DIMENSIONS

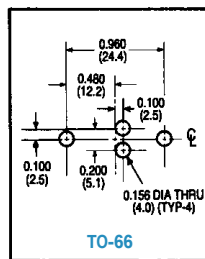


690 SERIES

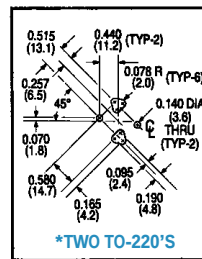
SEMICONDUCTOR MOUNTING HOLES



TO-3

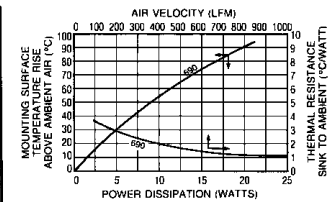


TO-66



*TWO TO-220'S

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Dimensions: in. (mm)



680 SERIES Maximum Efficiency Omnidirectional Heat Sinks

TO-3, TO-220

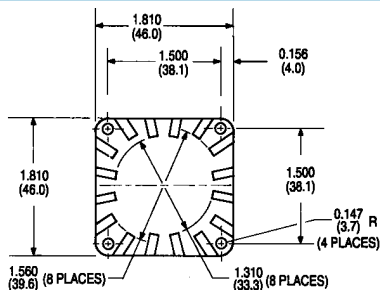
Standard P/N	Height Above PC Board "A" in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
680-5A ▲	0.500 (12.7)	1.810 (46.0)-sq	70°C @ 7.5W	3.0°C/W @ 400 LFM	(1) TO-3	0.0700 (31.75)
680-75A ▲	0.750 (19.1)	1.810 (46.0)-sq	58°C @ 7.5W	2.4°C/W @ 400 LFM	(1) TO-3	0.0900 (40.82)
680-10A ▲	1.000 (25.4)	1.810 (46.0)-sq	52°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-3	0.0980 (44.45)
680-125A ▲	1.250 (31.8)	1.810 (46.0)-sq	45°C @ 7.5W	1.5°C/W @ 400 LFM	(1) TO-3	0.1100 (49.90)
680-5220	0.500 (12.7)	1.810 (46.0)-sq	70°C @ 7.5W	3.0°C/W @ 400 LFM	(2) TO-220	0.0700 (31.75)
680-75220	0.750 (19.1)	1.810 (46.0)-sq	58°C @ 7.5W	2.4°C/W @ 400 LFM	(2) TO-220	0.0900 (40.82)
680-10220 ▲	1.000 (25.4)	1.810 (46.0)-sq	52°C @ 7.5W	2.0°C/W @ 400 LFM	(2) TO-220	0.0980 (44.45)
680-125220 ▲	1.250 (31.8)	1.810 (46.0)-sq	45°C @ 7.5W	1.5°C/W @ 400 LFM	(2) TO-220	0.1100 (49.90)

Material: Aluminum, Black Anodized

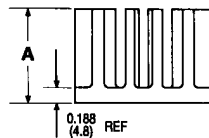
Achieve optimum natural convection cooling per unit volume occupied above the printed circuit board for TO-3 (one semiconductor package per heat sink) or for two TO-220 style cases, when this low-cost heat sink is used. Any mounting attitude will provide free circulation

of air in natural convection applications. These 680 Series heat sinks can also be specified without any semiconductor mounting hole pattern by specifying suffix "K" (Example: 680-5K).

MECHANICAL DIMENSIONS

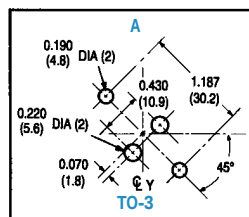


680 SERIES

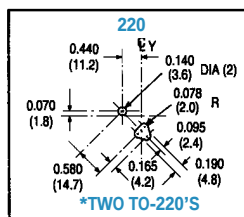


Dimensions: in. (mm)

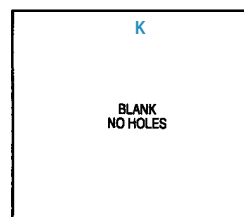
SEMICONDUCTOR MOUNTING HOLES



TO-3

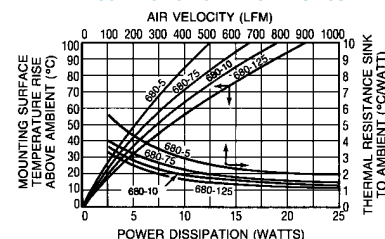


*TWO TO-220'S



BLANK NO HOLES

NATURAL AND FORCED CONVECTION CHARACTERISTICS



*Only one hole pattern of two is shown. Hole patterns are symmetrical about the center lines.

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



601 AND 603 SERIES Low-Height Heat Sinks

DO-4/DO-5 Diodes

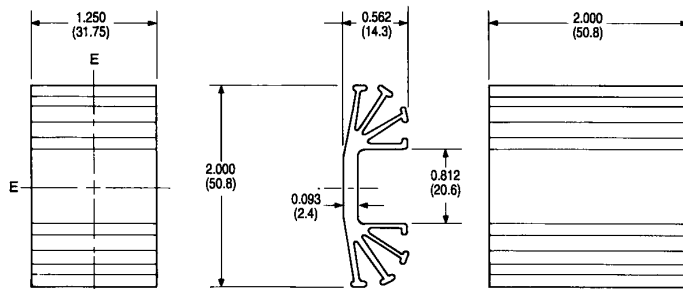
Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Mounting Hole Dia. in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
601E	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	0.200 (5.1)	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
601F	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	0.270 (6.9)	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
601K	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	None	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
603K	2.000 (50.8) x 2.000 (50.8)	0.562 (14.3)	None	41°C @ 5.0W	4.0°C/W @ 175 LFM	0.0810 (36.74)

Material: Aluminum Alloy, Black Anodized

Use these low-height heat sinks on printed circuit board applications for TO-66 power semiconductors and DO-4 and DO-5 diodes, where close board-to-board spacing and efficient

heat dissipation are required. The 601 and 603 Series may also be attached to enclosure panels or brackets using isolation hardware where necessary.

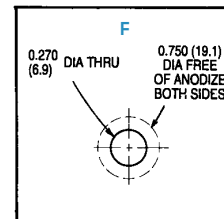
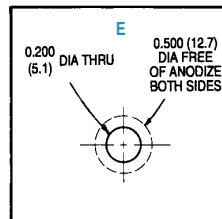
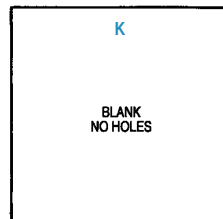
MECHANICAL DIMENSIONS



601 SERIES
(EXTRUSION PROFILE 1284)

603 SERIES
(EXTRUSION PROFILE 1284)

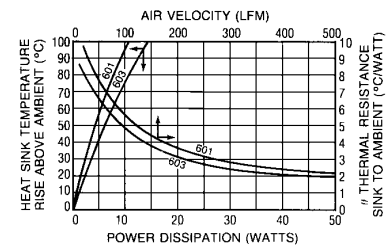
SEMICONDUCTOR MOUNTING HOLES



Dimensions: in. (mm)

E&F available on 601 Series only as a standard product.

NATURAL AND FORCED CONVECTION CHARACTERISTICS



635 SERIES Space-Saving Low-Cost Heat Sinks

TO-3

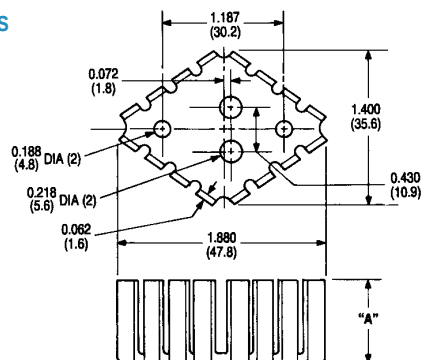
Standard P/N	Height Above PC Board "A" in. (mm)	Outline Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
635-5B2	0.500 (12.7)	1.900 (48.3) x 1.420 (36.0)	90°C @ 8.0W	6.0°C/W @ 300 LFM	TO-3	0.0200 (9.07)
635-75B2	0.750 (19.1)	1.900 (48.3) x 1.420 (36.0)	77°C @ 8.0W	4.8°C/W @ 300 LFM	TO-3	0.0220 (9.98)
635-10B2	1.000 (25.4)	1.900 (48.3) x 1.420 (36.0)	61°C @ 8.0W	3.6°C/W @ 300 LFM	TO-3	0.024 (10.89)
635-125B2	1.250 (31.8)	1.900 (48.3) x 1.420 (36.0)	53°C @ 8.0W	3.1°C/W @ 300 LFM	TO-3	0.028 (12.70)

Material: Aluminum Alloy, Black Anodized

Use this low-cost TO-3 heat sink style for multiple TO-3 applications on a single printed circuit board, where two or more TO-3s must be placed in proximity and minimum space is

available for heat sinking. Four different heights are available, all with TO-3 mounting hole pattern in the base. Consult factory for TO-66, TO-220, and multilead IC hole patterns.

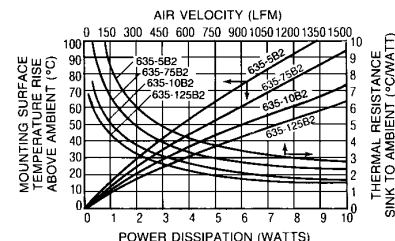
MECHANICAL DIMENSIONS



635 SERIES

Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Данный компонент на территории Российской Федерации

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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